Title (en)

Electrolytic copper plating method

Title (de)

Procédé de dépôt électrolytique de cuivre

Title (fr)

Verfahren zur elektrolytischen Kupferplattierung

Publication

EP 1741804 B1 20160427 (EN)

Application

EP 06253410 A 20060629

Priority

US 69783305 P 20050708

Abstract (en)

[origin: EP1741804A1] Copper plating baths containing a leveling agent that is a reaction product of a compound including a heteroatom chosen from nitrogen, sulfur and a mixture of nitrogen and sulfur, with a polyepoxide compound containing an ether linkage that deposit copper on the surface of an electronic device and in apertures on such substrate are provided. Such plating baths deposit a copper layer on the substrate surface that is substantially planar across a range of electrolyte concentrations. Methods of depositing copper layers using such copper plating baths are also disclosed.

IPC 8 full level

C25D 3/38 (2006.01)

CPC (source: EP KR US)

C25D 3/38 (2013.01 - EP KR US); **H05K 3/423** (2013.01 - EP KR US); H05K 2201/09509 (2013.01 - KR); H05K 2201/09563 (2013.01 - EP KR US)

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EP 06253410 A 20060629; CN 200610101330 A 20060707; JP 2006186340 A 20060706; KR 20060063929 A 20060707; TW 95124764 A 20060707; US 48289006 A 20060707